

HSB0104YP

Silicon Schottky Barrier Diode for High Speed Switching

REJ03G0597-0200
(Previous: ADE-208-730A)
Rev.2.00
Apr 12, 2005

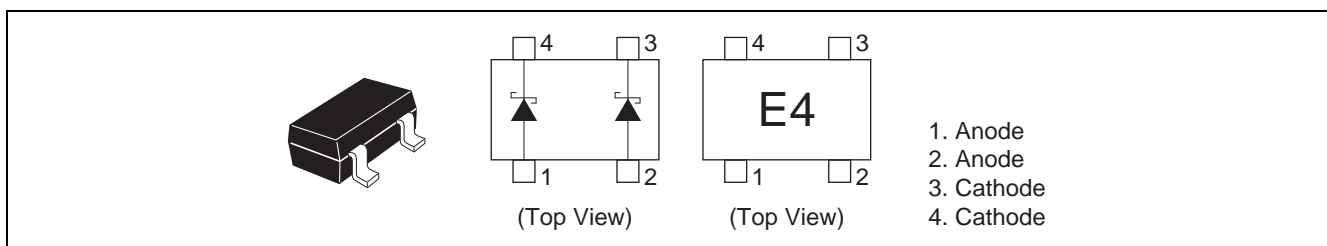
Features

- Can be used for protection of signal-bus lines.
- The mounting efficiency has been improved by incorporating two low-loss diode element into a CMPAK-4 package.

Ordering Information

Type No.	Laser Mark	Package Name	Package Code (Previous Code)
HSB0104YP	E4	CMPAK-4	PTSP0004ZB-A (CMPAK-4)

Pin Arrangement



Absolute Maximum Ratings *1

(Ta = 25°C)

Item	Symbol	Value	Unit
Reverse peak reverse voltage	V_{RRM}	40	V
Forward current	I_F	100	mA
Non-Repetitive peak forward surge current	I_{FSM} *2	3	A
Junction temperature	T_j	125	°C
Storage temperature	T_{stg}	-55 to +125	°C

- Notes: 1. Per one device.
 2. 10ms sine wave 1 pulse.

Electrical Characteristics

(Ta = 25°C)

Item	Symbol	Min	Typ	Max	Unit	Test Condition
Forward voltage	V_F	—	—	0.58	V	$I_F = 100\text{mA}$
Reverse current	I_R	—	—	50	μA	$V_R = 40\text{V}$
Capacitance	C	—	20	—	pF	$V_R = 0\text{V}, f = 1\text{MHz}$

Main Characteristic

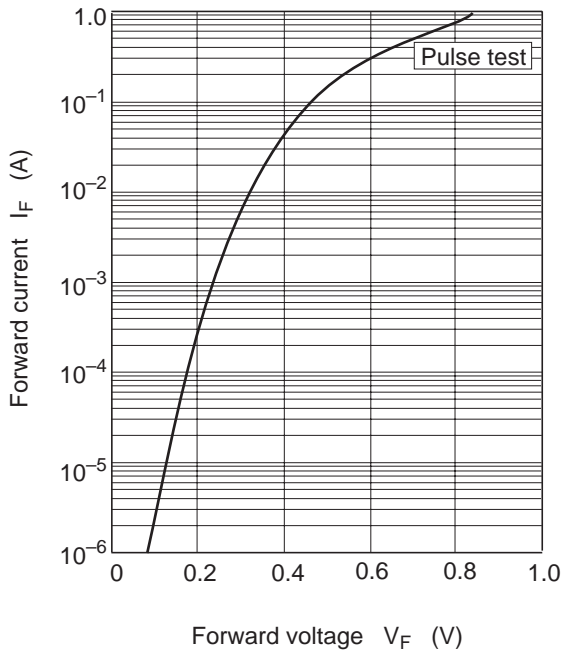


Fig.1 Forward current vs. Forward voltage

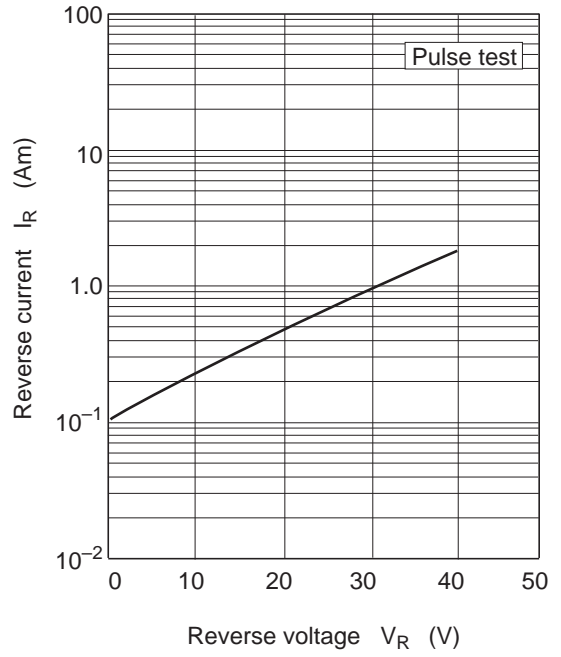


Fig.2 Reverse current vs. Reverse voltage

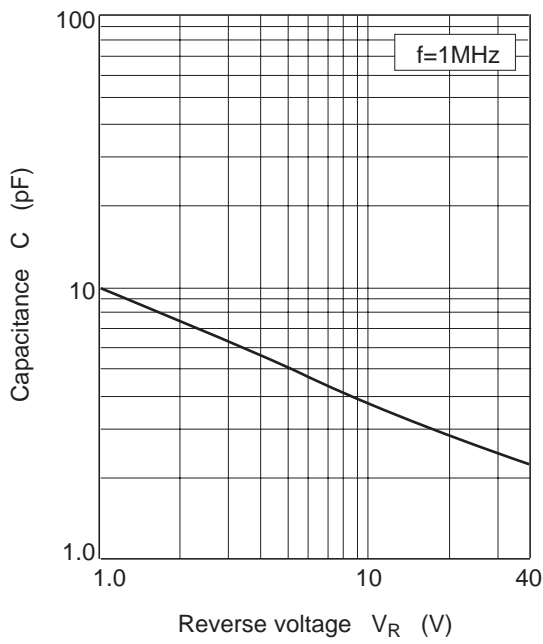
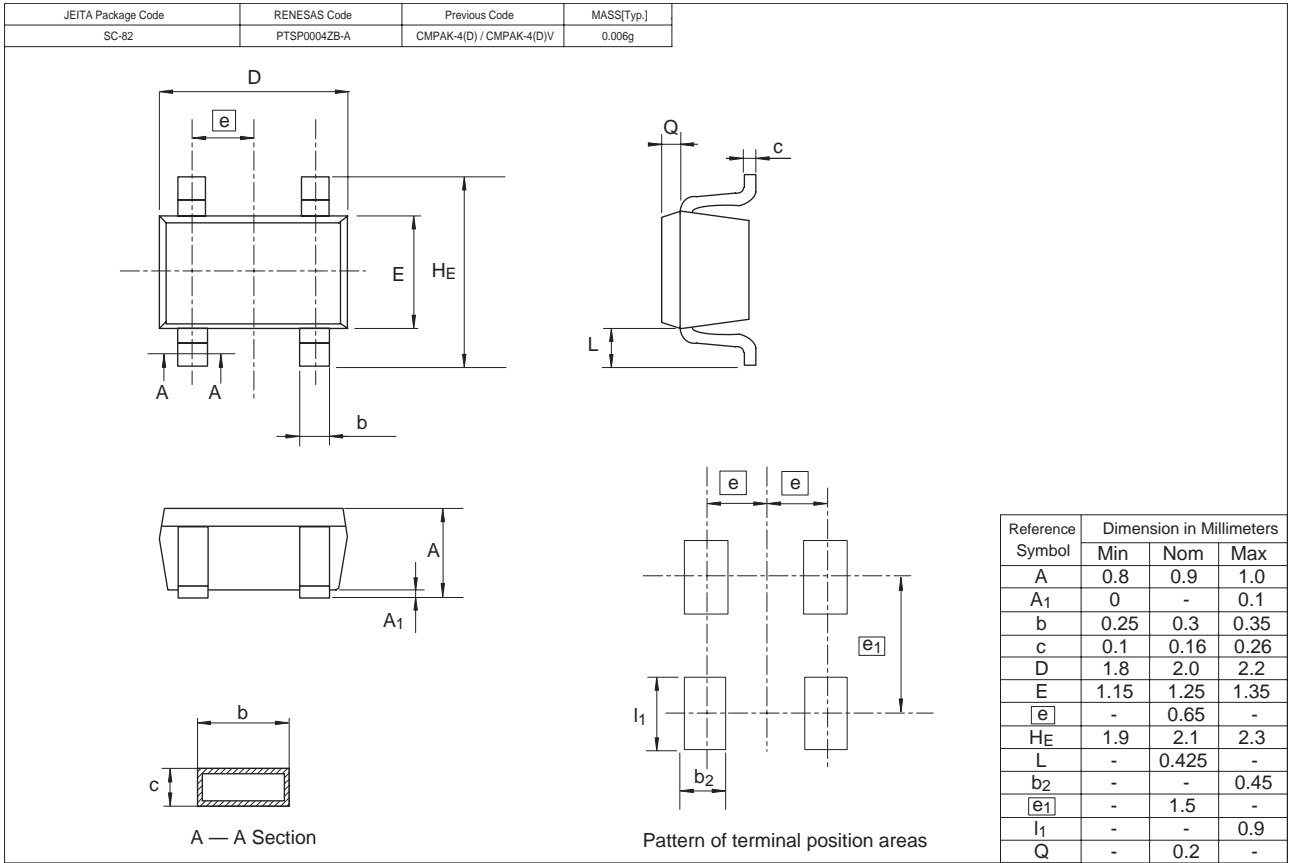


Fig.3 Capacitance vs. Reverse voltage

Package Dimensions



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